



Material Content Data Sheet



Sales Product Name		BCX 56 H6327		Issued		20. July 2018		
MA#		MA001202512						
Package		PG-SOT89-4-3		Weight*		53.15 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	noble metal	gold	7440-57-5	0.011	0.02		200	
	non noble metal	tin	7440-31-5	0.003	0.01		51	
	inorganic material	silicon	7440-21-3	0.129	0.24	0.27	2436	2687
leadframe	inorganic material	silicon	7440-21-3	0.005	0.01		95	
	non noble metal	titanium	7440-32-6	0.025	0.05		474	
	non noble metal	chromium	7440-47-3	0.076	0.14		1423	
	non noble metal	copper	7440-50-8	25.112	47.23	47.43	472478	474470
wire	non noble metal	copper	7440-50-8	0.051	0.10	0.10	953	953
encapsulation	organic material	carbon black	1333-86-4	0.269	0.51		5054	
	plastics	epoxy resin	-	4.029	7.58		75815	
	inorganic material	silicondioxide	60676-86-0	22.565	42.46	50.55	424562	505431
leadfinish	non noble metal	tin	7440-31-5	0.801	1.51	1.51	15076	15076
plating	noble metal	silver	7440-22-4	0.073	0.14	0.14	1383	1383
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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